

RECEIVED  
CENTRAL FAX CENTER

JUN 01 2006

S/N 10/826091

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	KAWAGUCHI, ET AL.	Examiner:	M. E. LAVILLA
Serial No.:	10/826091	Group Art Unit:	1775
Filed:	April 16, 2004	Docket No.:	10873.1436US01
Title:	BONDING LAYER FORMING SOLUTION, METHOD OF PRODUCING COPPER-TO-RESIN BONDING LAYER USING THE SOLUTION, AND LAYERED PRODUCT OBTAINED THEREBY		

CERTIFICATE UNDER 37 CFR 1.6(d):I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on  
June 1, 2006By: 

Chieko Rogers

AMENDMENT AND RESPONSE

Mail Stop: AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Dear Sir:

In response to the Office Action dated March 3, 2006 and Advisory Action dated  
May 23, 2006, please amend the above-identified application as follows:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.

*OK to enter  
am  
6/16/06*